

FIG. 1

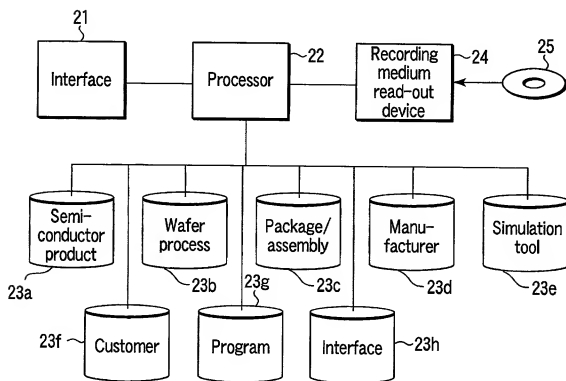


FIG. 2

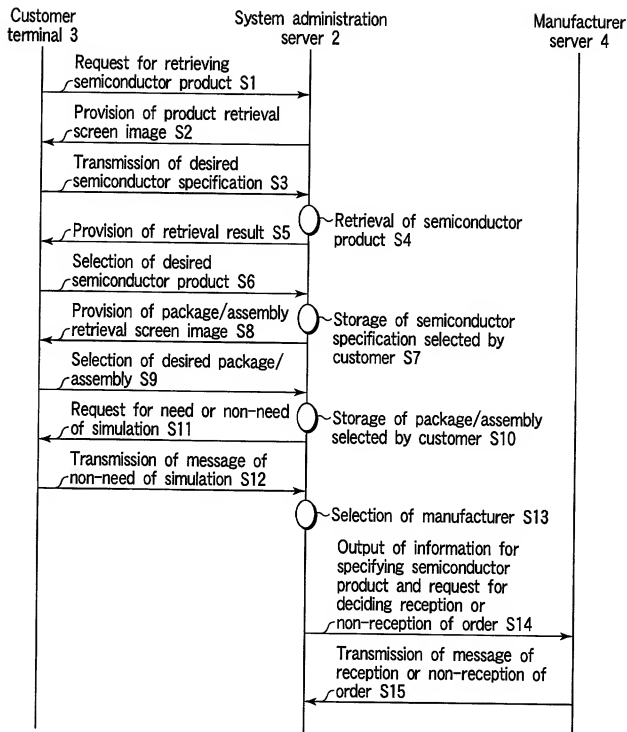


FIG. 3

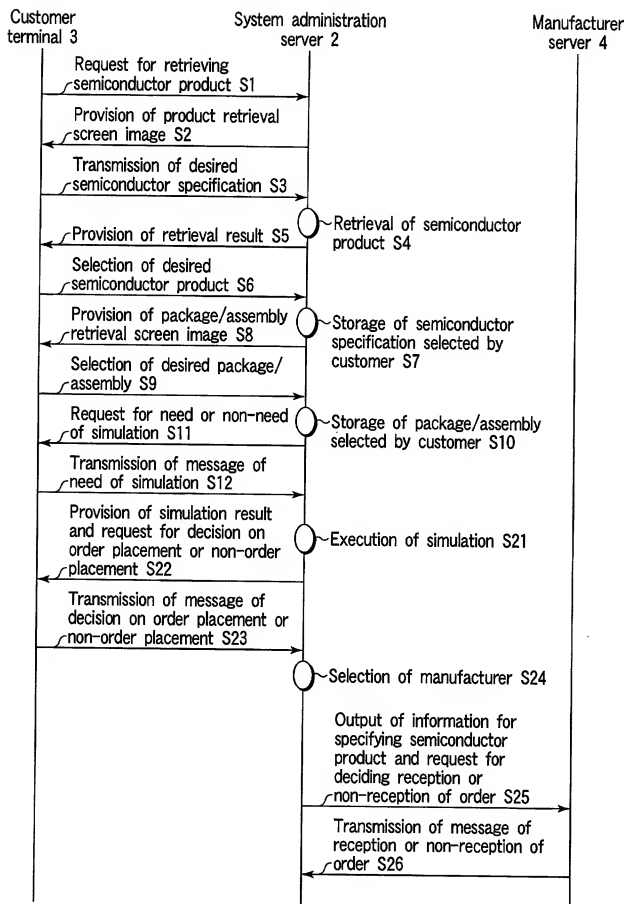


FIG. 4

Select type of semiconductor product.
Also select specification of device you want to by selected
from list of typical devices below.

Memory	
Logic	
System LSI	
Others	

Input necessary specification.

Operation frequency MHz ~ MHz

Cost ¥ ~ ¥

Delivery date Not later than (month), (day) OK Cancel

FIG.5

Select product conforming to your specification form semiconductor products listed below.

System LSI, 800MHz	<input type="checkbox"/>
System LSI, 833MHz	<input type="checkbox"/>
System LSI, 850MHz	<input type="checkbox"/>

FIG. 6

Select or input values for package and/or assembly
you want from below.

Size		mm2	~	mm2
External form		<input type="radio"/> BGA	<input type="radio"/> DIP	<input type="radio"/> QFP
Package type		<input type="radio"/> Single chip		<input type="radio"/> Multi-chip
Package structure		<input type="radio"/> Single layer		<input type="radio"/> Multilayer
Inner lead bonding modes		<input type="radio"/> C4	<input type="radio"/> TAB	<input type="radio"/> Wire
Packing type for shipment				

FIG. 7

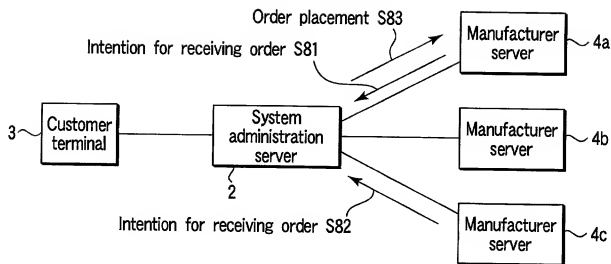


FIG. 8

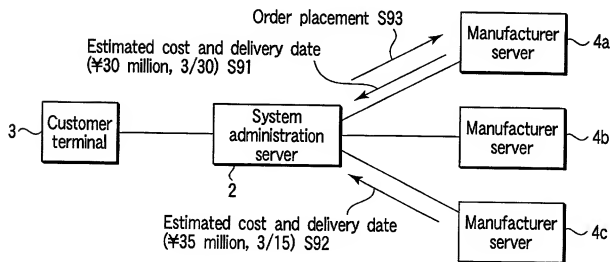


FIG. 9

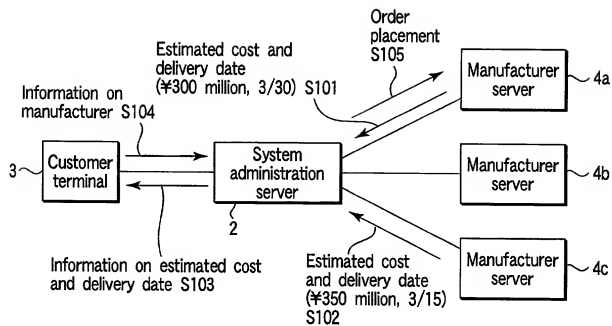


FIG. 10

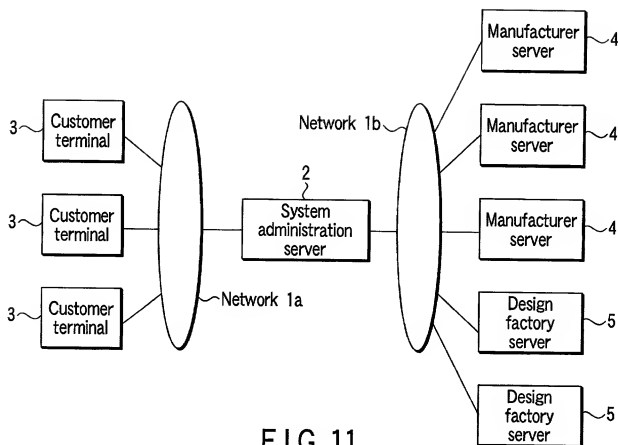


FIG. 11

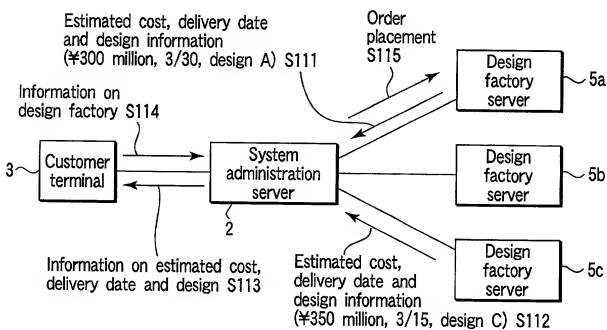


FIG. 12

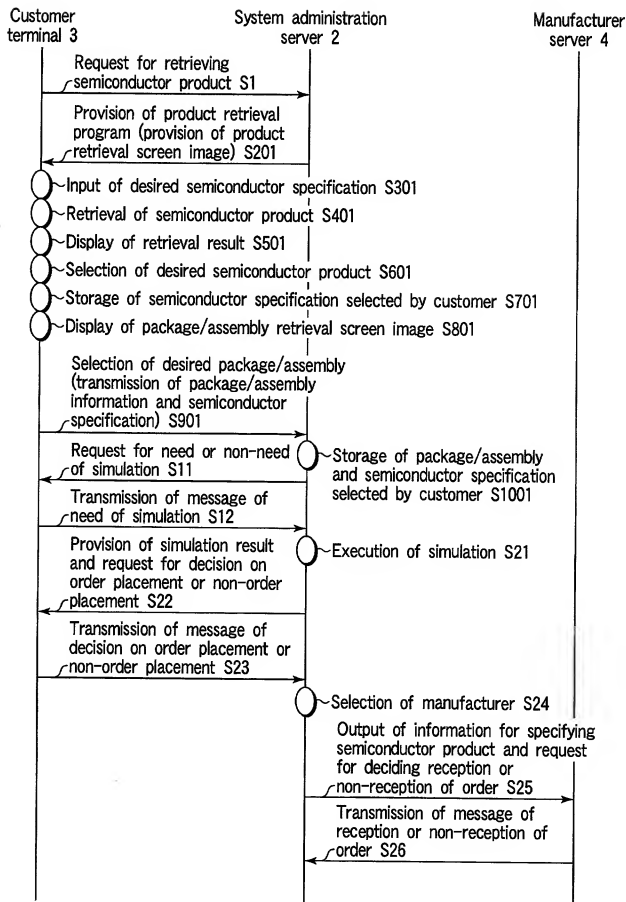


FIG. 13